



## Final Product Change Notification

201912030F01

**Issue Date:** 12-Jan-2020

**Effective Date:** 11-Apr-2020

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



# QUALITY

**This notice is NXP Company Proprietary.**

### Management Summary

The LPC54(S)018Jx products are changing to revision 1C for improved bondability.

#### Change Category

<input checked="" type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

LPC54(S)018JxM Revision Change to 1C for Wirebond Improvement

### Description of Change

The LPC54(S)018JxM products have been upgraded to include an additional metal layer on the serial flash die for improved for wire bonding.

The product revision changes from "1B" to "1C".

The LPC microcontroller die and package does not change.

#### Reason for Change

To improve the wire bonding performance for high volume manufacturing.

#### Identification of Affected Products

Top side marking

The last character of the last line in the top side marking changes from "B" to "C".

## Product Availability

### Sample Information

Samples are available upon request

### Production

Planned first shipment 10-Apr-2020

## Anticipated Impact on Form, Fit, Function, Reliability or Quality

The last character of the last line in the top side marking changes from "B" to "C".

### Data Sheet Revision

No impact to existing datasheet

### Disposition of Old Products

Existing inventory will be shipped until depleted

## Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 11-Feb-2020.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

## About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[View Notification](#)

[Subscription](#)

[Support](#)

[NXP](#) | [Privacy Policy](#) | [Terms of Use](#)

NXP Semiconductors  
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.

### Affected Part Numbers

LPC54018J2MET180E

LPC54S018J4MET180E

LPC54S018J2MET180E

LPC54018J4MET180E